

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#4a
NEAK

Applicant: KENJI HORII ET AL.

Serial No.: Not Yet Assigned Group Art Unit:

Filed: December 14, 2000 Examiner:

Title: METHOD OF BONDING METAL PLATES, APPARATUS
THEREFORE AND HOT STRIP MILL

PRELIMINARY AMENDMENT

Box APPLICATION
Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination and before calculation of fees, please
preliminarily amend the above-identified application filed
herewith as follows:

IN THE SPECIFICATION:

Page 1, line 5, insert the following paragraph:

-- This application claims the priority of Japanese Patent
Application No. 11-345215, filed in Japan December 14, 1999, and
Japanese Patent Application No. 2000-316522, filed in Japan
October 17, 2000, the disclosures of which are expressly
incorporated by reference herein.

0011-345215

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